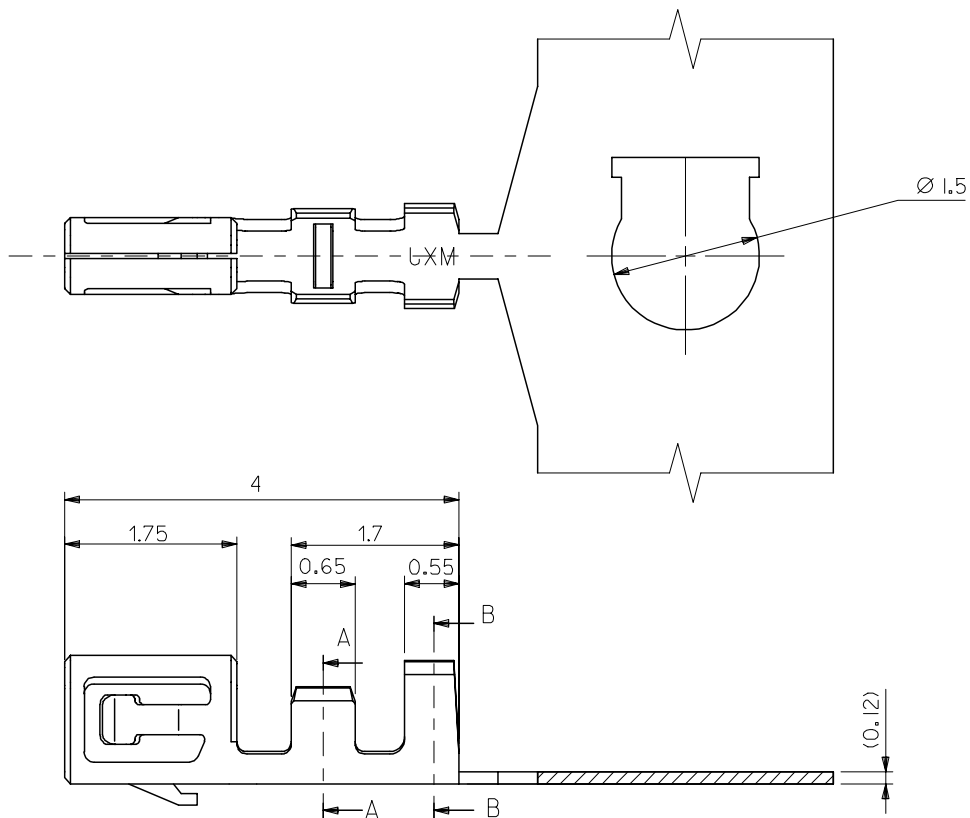


NOTES.

- 適合ハウジング: 501189-****
APPLICABLE HOUSING : 501189-****
- メッキ仕様
PLATING
金メッキ: 0.1 μ m MIN.
Au PLATING
ニッケルメッキ (下地): 1.0 μ m MIN.
Ni PLATING (UNDER PLATING)

501193-0100	バラ状 LOOSE
501193-0000	連鎖状 CHAIN
MATERIAL NO.	端子形状 FORM

MATERIAL リン青銅 PHOSPHOR BRONZE +0.12		REVISED EC NO: J2005-0329 DRAWN: NYOSHIDA 2004/11/02 CHKD: MYAGI 2004/11/02 APPR: ANODA 2004/11/12 A	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	TITLE 1.0 WIRE TO BOARD CONN. CRIMP REC TERMINAL			
FINISH SEE NOTE				10 UNDER	±0.2	DRAWN BY DATE NYOSHIDA 2004/04/03		APPROVED BY DATE MIYAZAWA 2004/04/03				MOLEX MOLEX INCORPORATED		
WIRE RANGE AWG#28-32				10 OVER 30 UNDER	±0.25	CHECKED BY DATE MYAGI 2004/04/03		MATERIAL NO. SEE CHART					DOCUMENT NO. SD-501193-001	SHEET NO. 1 OF 1
INS. RANGE ø 0.4-0.8				30 OVER	±0.3	APPROVED BY DATE MIYAZAWA 2004/04/03		MATERIAL NO. SEE CHART					DOCUMENT NO. SD-501193-001	SHEET NO. 1 OF 1
				ANGULAR ±3 °			SIZE A 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS										